# **74AUP1G38**

# Low-power 2-input NAND gate (open drain)

Rev. 7 — 4 April 2016

**Product data sheet** 

### 1. General description

The 74AUP1G38 provides the single 2-input NAND gate with open-drain output. The output of the device is an open drain and can be connected to other open-drain outputs to implement active-LOW wired-OR or active-HIGH wired-AND functions.

Schmitt trigger action at all inputs makes the circuit tolerant to slower input rise and fall times across the entire  $V_{CC}$  range from 0.8 V to 3.6 V.

This device ensures a very low static and dynamic power consumption across the entire  $V_{CC}$  range from 0.8 V to 3.6 V.

This device is fully specified for partial power-down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

### 2. Features and benefits

- Wide supply voltage range from 0.8 V to 3.6 V
- High noise immunity
- Complies with JEDEC standards:
  - ◆ JESD8-12 (0.8 V to 1.3 V)
  - ◆ JESD8-11 (0.9 V to 1.65 V)
  - ◆ JESD8-7 (1.2 V to 1.95 V)
  - ◆ JESD8-5 (1.8 V to 2.7 V)
  - ◆ JESD8-B (2.7 V to 3.6 V)
- ESD protection:
  - ♦ HBM JESD22-A114F Class 3A exceeds 5000 V
  - ♦ MM JESD22-A115-A exceeds 200 V
  - ◆ CDM JESD22-C101E exceeds 1000 V
- Low static power consumption;  $I_{CC} = 0.9 \mu A$  (maximum)
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Inputs accept voltages up to 3.6 V
- Low noise overshoot and undershoot < 10 % of V<sub>CC</sub>
- I<sub>OFF</sub> circuitry provides partial power-down mode operation
- Multiple package options
- Specified from -40 °C to +85 °C and -40 °C to +125 °C



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# 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74AUP1G38GW	–40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1
74AUP1G38GM	–40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 $\times$ 1.45 $\times$ 0.5 mm	SOT886
74AUP1G38GF	–40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 $\times$ 1 $\times$ 0.5 mm	SOT891
74AUP1G38GN	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body $0.9 \times 1.0 \times 0.35$ mm	SOT1115
74AUP1G38GS	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 1.0 $\times$ 1.0 $\times$ 0.35 mm	SOT1202
74AUP1G38GX	-40 °C to +125 °C	X2SON5	X2SON5: plastic thermal enhanced extremely thin small outline package; no leads; 5 terminals; body $0.8 \times 0.8 \times 0.35$ mm	SOT1226

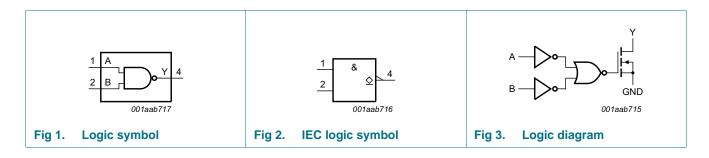
## 4. Marking

#### Table 2. Marking

Type number	Marking code <sup>[1]</sup>
74AUP1G38GW	аВ
74AUP1G38GM	аВ
74AUP1G38GF	аВ
74AUP1G38GN	аВ
74AUP1G38GS	аВ
74AUP1G38GX	аВ

<sup>[1]</sup> The pin 1 indicator is located on the lower left corner of the device, below the marking code.

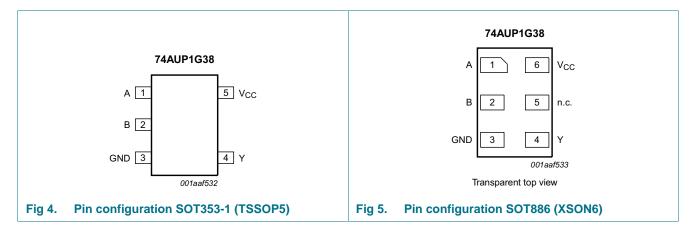
# 5. Functional diagram



**Low-power 2-input NAND gate (open drain)** 

# 6. Pinning information

### 6.1 Pinning





### 6.2 Pin description

Table 3. Pin description

Symbol	Pin	Description	
	TSSOP5 and X2SON5	XSON6	
A	1	1	data input
В	2	2	data input
GND	3	3	ground (0 V)
Υ	4	4	data output
n.c.	-	5	not connected
V <sub>CC</sub>	5	6	supply voltage

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## 7. Functional description

Table 4. Function table[1]

Input		Output
A B		Υ
L	L	Z
L	Н	Z
Н	L	Z
Н	Н	L

<sup>[1]</sup> H = HIGH voltage level;

# 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>CC</sub>	supply voltage			-0.5	+4.6	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < 0 V		-50	-	mA
V <sub>I</sub>	input voltage		<u>[1]</u>	-0.5	+4.6	V
I <sub>OK</sub>	output clamping current	V <sub>O</sub> < 0 V		-50	-	mA
Vo	output voltage	Active mode and Power-down mode	<u>[1]</u>	-0.5	+4.6	V
Io	output current	$V_O = 0 \text{ V to } V_{CC}$		-	+20	mA
I <sub>CC</sub>	supply current			-	+50	mA
I <sub>GND</sub>	ground current			-50	-	mA
T <sub>stg</sub>	storage temperature			-65	+150	°C
P <sub>tot</sub>	total power dissipation	$T_{amb} = -40  ^{\circ}\text{C} \text{ to } +125  ^{\circ}\text{C}$	[2]	-	250	mW

<sup>[1]</sup> The minimum input and output voltage ratings may be exceeded if the input and output current ratings are observed.

# 9. Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		0.8	3.6	V
V <sub>I</sub>	input voltage		0	3.6	V
Vo	output voltage	Active mode and Power-down mode	0	3.6	V
T <sub>amb</sub>	ambient temperature		-40	+125	°C
Δt/ΔV	input transition rise and fall rate	V <sub>CC</sub> = 0.8 V to 3.6 V	0	200	ns/V

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L = LOW voltage level;

Z = high-impedance OFF state.

<sup>[2]</sup> For TSSOP5 packages: above 87.5 °C the value of  $P_{tot}$  derates linearly with 4.0 mW/K. For XSON6 and X2SON5 packages: above 118 °C the value of  $P_{tot}$  derates linearly with 7.8 mW/K.

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## 10. Static characteristics

Table 7. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
T <sub>amb</sub> = 2	5 °C					1
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 0.8 V	$0.70 \times V_{CC}$	-	-	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	$0.65 \times V_{CC}$	-	-	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.6	-	-	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.0	-	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 0.8 V	-	-	$0.30 \times V_{CC}$	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	-	-	$0.35 \times V_{CC}$	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	-	0.7	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	-	0.9	V
V <sub>OL</sub>	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$				
		$I_O = 20 \mu A$ ; $V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	0.1	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	$0.3 \times V_{CC}$	V
		I <sub>O</sub> = 1.7 mA; V <sub>CC</sub> = 1.4 V	-	-	0.31	V
		I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V	-	-	0.31	V
		$I_{O}$ = 2.3 mA; $V_{CC}$ = 2.3 V	-	-	0.31	V
		$I_O = 3.1 \text{ mA}; V_{CC} = 2.3 \text{ V}$	-	-	0.44	V
		$I_O = 2.7 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	-	0.31	V
		$I_O = 4.0 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	-	0.44	V
l <sub>l</sub>	input leakage current	$V_{I} = GND \text{ to } 3.6 \text{ V}; V_{CC} = 0 \text{ V to } 3.6 \text{ V}$	-	-	±0.1	μΑ
l <sub>OZ</sub>	OFF-state output current	$V_I = V_{IH}$ or $V_{IL}$ (and at least one input LOW); $V_O = 0$ V to 3.6 V; $V_{CC} = 0$ V to 3.6 V	-	-	±0.1	μΑ
I <sub>OFF</sub>	power-off leakage current	$V_{I}$ or $V_{O} = 0 \text{ V}$ to 3.6 V; $V_{CC} = 0 \text{ V}$	-	-	±0.2	μΑ
$\Delta I_{OFF}$	additional power-off leakage current	V <sub>1</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V to 0.2 V	-	-	±0.2	μΑ
I <sub>CC</sub>	supply current	$V_1 = GND \text{ or } V_{CC}; I_O = 0 \text{ A};$ $V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	0.5	μΑ
Δl <sub>CC</sub>	additional supply current	$V_I = V_{CC} - 0.6 \text{ V}; I_O = 0 \text{ A}; V_{CC} = 3.3 \text{ V}$	-	-	40	μΑ
Cı	input capacitance	$V_{CC} = 0 \text{ V to } 3.6 \text{ V; } V_{I} = \text{GND or } V_{CC}$	-	8.0	-	pF
Co	output capacitance	output enabled; $V_O = GND$ ; $V_{CC} = 0 V$	-	1.7	-	pF
		output disabled; V <sub>O</sub> = GND; V <sub>CC</sub> = 0 V	-	1.1	-	pF
T <sub>amb</sub> = -	40 °C to +85 °C		,		•	-
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 0.8 V	$0.70 \times V_{CC}$	-	-	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	0.65 × V <sub>CC</sub>	-	-	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.6	-	-	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.0	-	-	V

Low-power 2-input NAND gate (open drain)

 Table 7.
 Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 0.8 V	-	-	$0.30 \times V_{CC}$	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	-	-	$0.35 \times V_{CC}$	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	-	0.7	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	-	0.9	V
V <sub>OL</sub>	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$				
		$I_{O}$ = 20 $\mu$ A; $V_{CC}$ = 0.8 $V$ to 3.6 $V$	-	-	0.1	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	$0.3 \times V_{CC}$	V
		I <sub>O</sub> = 1.7 mA; V <sub>CC</sub> = 1.4 V	-	-	0.37	V
		I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V	-	-	0.35	V
		$I_{O} = 2.3 \text{ mA}; V_{CC} = 2.3 \text{ V}$	-	-	0.33	V
		$I_{O} = 3.1 \text{ mA}; V_{CC} = 2.3 \text{ V}$	-	-	0.45	V
		$I_{O} = 2.7 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	-	0.33	V
		$I_{O} = 4.0 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	-	0.45	V
I <sub>I</sub>	input leakage current	$V_{I} = GND \text{ to } 3.6 \text{ V}; V_{CC} = 0 \text{ V to } 3.6 \text{ V}$	-	-	±0.5	μΑ
l <sub>OZ</sub>	OFF-state output current	$V_I = V_{IH}$ or $V_{IL}$ (and at least one input LOW); $V_O = 0$ V to 3.6 V; $V_{CC} = 0$ V to 3.6 V	-	-	±0.5	μΑ
I <sub>OFF</sub>	power-off leakage current	$V_{I}$ or $V_{O} = 0 \text{ V}$ to 3.6 V; $V_{CC} = 0 \text{ V}$	-	-	±0.5	μΑ
$\Delta I_{OFF}$	additional power-off leakage current	V <sub>1</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V to 0.2 V	-	-	±0.6	μΑ
I <sub>CC</sub>	supply current	$V_1 = GND \text{ or } V_{CC}; I_O = 0 \text{ A};$ $V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	0.9	μΑ
$\Delta I_{CC}$ $T_{amb} = -\epsilon$	additional supply current 40 °C to +125 °C	$V_1 = V_{CC} - 0.6 \text{ V}; I_O = 0 \text{ A}; V_{CC} = 3.3 \text{ V}$	-	-	50	μΑ
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 0.8 V	0.75 × V <sub>CC</sub>	-	-	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	0.70 × V <sub>CC</sub>	-	-	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.6	-	-	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.0	-	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 0.8 V	-	-	0.25 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	-	-	$0.30 \times V_{CC}$	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	-	0.7	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	-	0.9	V
V <sub>OL</sub>	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$				
		$I_O = 20 \mu A$ ; $V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	0.11	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	$0.33 \times V_{CC}$	V
		I <sub>O</sub> = 1.7 mA; V <sub>CC</sub> = 1.4 V	-	-	0.41	V
		I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V	-	-	0.39	V
		I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 2.3 V	-	-	0.36	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.50	V
		$I_{O} = 2.7 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	-	0.36	V
		$I_O = 4.0 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	-	0.50	V

Low-power 2-input NAND gate (open drain)

 Table 7.
 Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I <sub>I</sub>	input leakage current	$V_I = GND$ to 3.6 V; $V_{CC} = 0$ V to 3.6 V	-	-	±0.75	μΑ
l <sub>OZ</sub>	OFF-state output current	$V_I = V_{IH}$ or $V_{IL}$ (and at least one input LOW); $V_O = 0$ V to 3.6 V; $V_{CC} = 0$ V to 3.6 V	-	-	±0.75	μА
I <sub>OFF</sub>	power-off leakage current	$V_I$ or $V_O = 0$ V to 3.6 V; $V_{CC} = 0$ V	-	-	±0.75	μΑ
$\Delta I_{OFF}$	additional power-off leakage current	$V_1$ or $V_0 = 0$ V to 3.6 V; $V_{CC} = 0$ V to 0.2 V	-	-	±0.75	μΑ
I <sub>CC</sub>	supply current	$V_I$ = GND or $V_{CC}$ ; $I_O$ = 0 A; $V_{CC}$ = 0.8 V to 3.6 V	-	-	1.4	μΑ
$\Delta I_{CC}$	additional supply current	$V_I = V_{CC} - 0.6 \text{ V}; I_O = 0 \text{ A}; V_{CC} = 3.3 \text{ V}$	-	-	75	μΑ

# 11. Dynamic characteristics

#### Table 8. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V; for test circuit see Figure 9

Symbol	Parameter	Conditions		25 °C		-40	0 °C to +1	25 °C	Unit
			Min	Typ[1]	Max	Min	Max (85 °C)	Max (125 °C)	
C <sub>L</sub> = 5 p	F								
t <sub>pd</sub>	propagation delay	A or B to Y; see Figure 8							
		V <sub>CC</sub> = 0.8 V	-	13.5	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	1.9	4.6	10.4	1.8	11.4	12.6	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	1.5	3.3	6.5	1.4	7.4	8.2	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.2	2.9	5.1	1.1	5.9	6.5	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.0	2.2	3.8	0.9	4.5	4.9	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.9	2.3	4.0	0.8	4.5	4.9	ns
C <sub>L</sub> = 10	pF	-	1		1	1	1	1	
t <sub>pd</sub>	propagation delay	A or B to Y; see Figure 8 [2]							
		V <sub>CC</sub> = 0.8 V	-	16.3	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	2.3	5.6	12.3	2.1	13.7	15.1	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	1.8	4.1	7.6	1.7	8.8	9.7	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.6	3.8	6.1	1.4	7.1	7.8	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.4	2.9	4.6	1.2	5.4	5.9	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.3	3.2	5.7	1.1	6.4	7.0	ns
C <sub>L</sub> = 15	pF							1	
t <sub>pd</sub>	propagation delay	A or B to Y; see Figure 8 [2]							
		V <sub>CC</sub> = 0.8 V	-	19.0	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	2.6	6.6	14.2	2.4	15.8	17.4	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	2.1	4.8	8.7	1.9	10.1	11.1	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.9	4.6	7.6	1.7	8.5	9.3	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.6	3.6	5.6	1.5	6.3	6.9	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.6	4.1	7.5	1.4	8.3	9.1	ns

### Low-power 2-input NAND gate (open drain)

 Table 8.
 Dynamic characteristics ...continued

Voltages are referenced to GND (ground = 0 V; for test circuit see Figure 9

Symbol	Parameter	Conditions		25 °C		-40	0 °C to +1	25 °C	Unit
			Min	Typ[1]	Max	Min	Max (85 °C)	Max (125 °C)	
C <sub>L</sub> = 30 p	οF								
t <sub>pd</sub>	propagation delay	A or B to Y; see Figure 8 [2]							
		V <sub>CC</sub> = 0.8 V	-	27.0	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	3.6	9.5	19.5	3.2	21.8	24.0	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	2.9	7.0	11.5	2.6	13.6	15.0	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	2.6	7.0	12.1	2.3	13.3	14.6	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	2.4	5.4	8.9	2.1	9.9	10.9	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.3	6.5	12.7	2.1	13.9	15.3	ns
C <sub>L</sub> = 5 pl	F, 10 pF, 15 pF and	30 pF			1				-1
C <sub>PD</sub>	power dissipation capacitance	$f_i = 1 \text{ MHz};$ [3] $V_I = \text{GND to } V_{CC}$							
		V <sub>CC</sub> = 0.8 V	-	0.6	-	-	-	-	рF
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	0.7	-	-	-	-	рF
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	0.8	-	-	-	-	рF
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	0.9	-	-	-	-	pF
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	1.1	-	-	-	-	pF
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	1.4	-	-	-	-	pF

<sup>[1]</sup> All typical values are measured at nominal  $V_{CC}$ .

 $P_D = C_{PD} \times V_{CC}{}^2 \times f_i \times N$  where:

 $f_i$  = input frequency in MHz;

V<sub>CC</sub> = supply voltage in V;

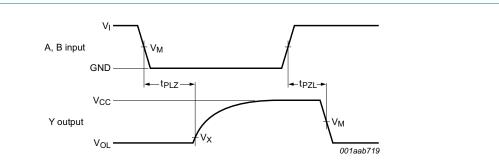
N = number of inputs switching.

<sup>[2]</sup>  $t_{pd}$  is the same as  $t_{PZL}$  and  $t_{PLZ}$ .

<sup>[3]</sup>  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu W$ ).

Low-power 2-input NAND gate (open drain)

### 12. Waveforms



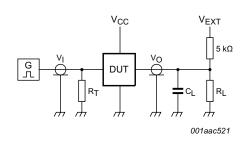
Measurement points are given in Table 9.

Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage drop that occur with the output load.

Fig 8. The data input (A or B) to output (Y) propagation delays

Table 9. Measurement points

Supply voltage	Input	Output	
V <sub>CC</sub>	V <sub>M</sub>	V <sub>M</sub>	V <sub>X</sub>
0.8 V to 1.6 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	V <sub>OL</sub> + 0.1 V
1.65 V to 2.7 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	V <sub>OL</sub> + 0.15 V
3.0 V to 3.6 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	V <sub>OL</sub> + 0.3 V



Test data is given in Table 10.

Definitions for test circuit:

R<sub>L</sub> = Load resistance.

 $C_L$  = Load capacitance including jig and probe capacitance.

 $R_T$  = Termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.

 $V_{EXT}$  = External voltage for measuring switching times.

#### Fig 9. Test circuit for measuring switching times

Table 10. Test data

Supply voltage	Load	V <sub>EXT</sub>				
V <sub>CC</sub>	C <sub>L</sub>	R <sub>L</sub> [1]	t <sub>PLH</sub> , t <sub>PHL</sub>	t <sub>PZH</sub> , t <sub>PHZ</sub>	t <sub>PZL</sub> , t <sub>PLZ</sub>	
0.8 V to 3.6 V	5 pF, 10 pF, 15 pF and 30 pF	5 k $\Omega$ or 1 M $\Omega$	open	GND	$2 \times V_{CC}$	

[1] For measuring enable and disable times  $R_L$  = 5 k $\Omega$ , for measuring propagation delays, setup and hold times and pulse width  $R_L$  = 1 M $\Omega$ .

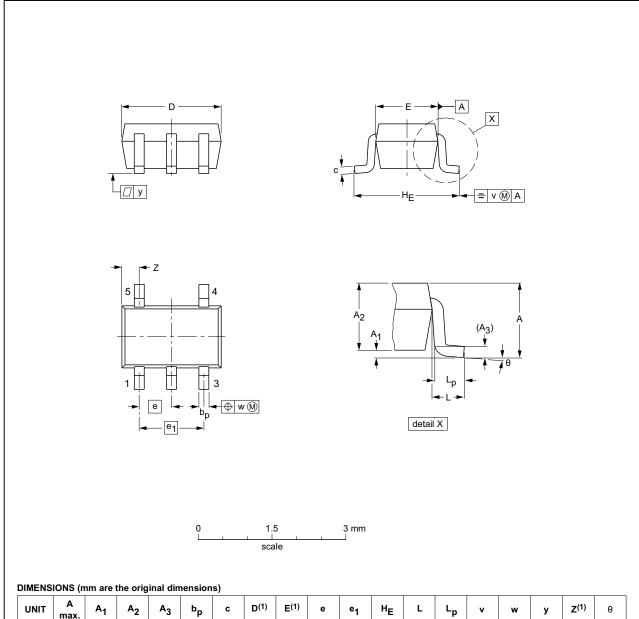
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# 13. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

SOT353-1



UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	bp	С	D <sup>(1)</sup>	E(1)	е	e <sub>1</sub>	HE	L	Lp	v	w	у	Z <sup>(1)</sup>	θ
mm	1.1	0.1 0	1.0 0.8	0.15	0.30 0.15	0.25 0.08	2.25 1.85	1.35 1.15	0.65	1.3	2.25 2.0	0.425	0.46 0.21	0.3	0.1	0.1	0.60 0.15	7° 0°

### Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	REFERENCES			ISSUE DATE
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT353-1		MO-203	SC-88A			<del>00-09-01</del> 03-02-19

Fig 10. Package outline SOT353-1 (TSSOP5)

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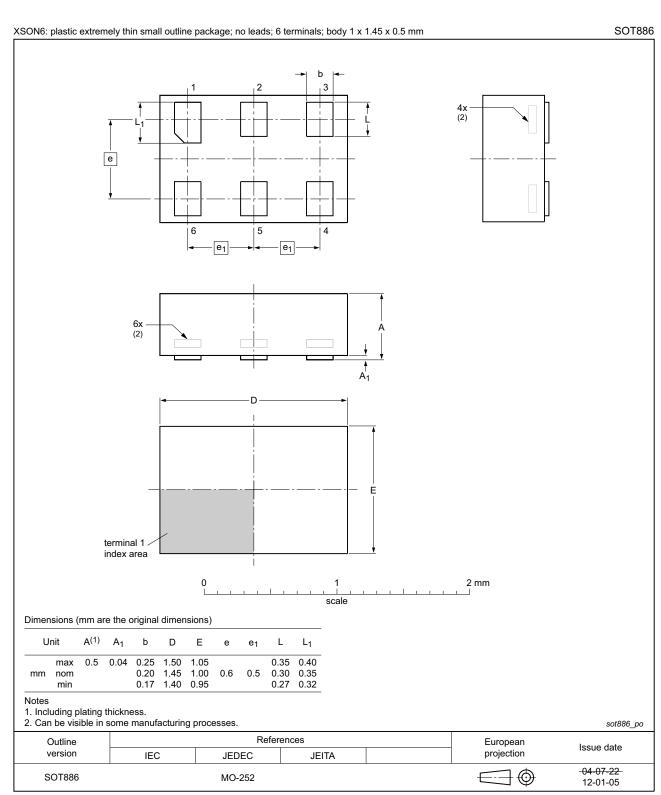


Fig 11. Package outline SOT886 (XSON6)

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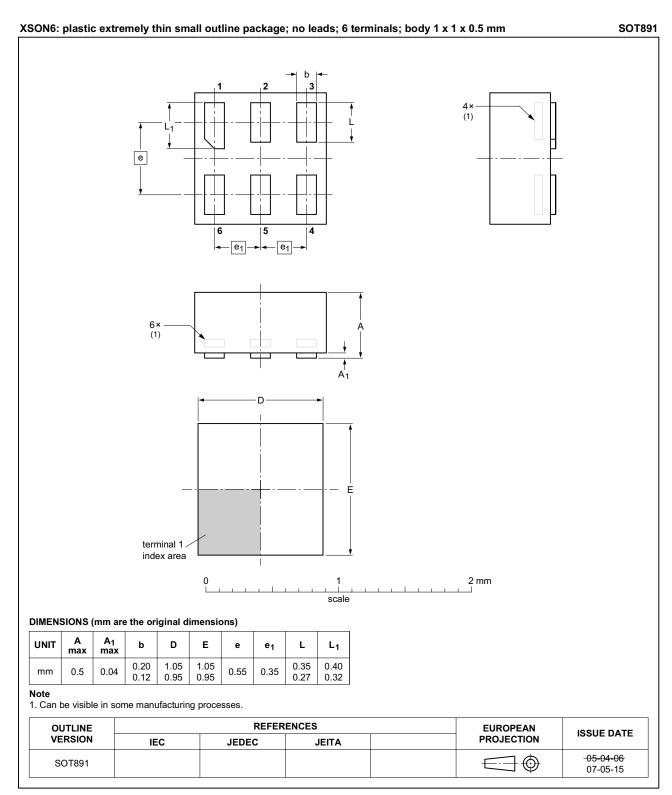


Fig 12. Package outline SOT891 (XSON6)

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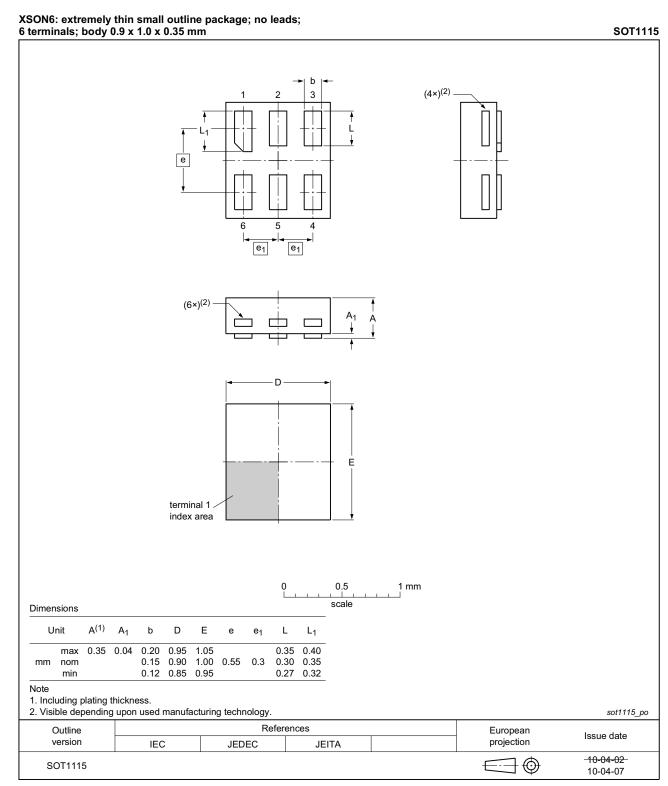


Fig 13. Package outline SOT1115 (XSON6)

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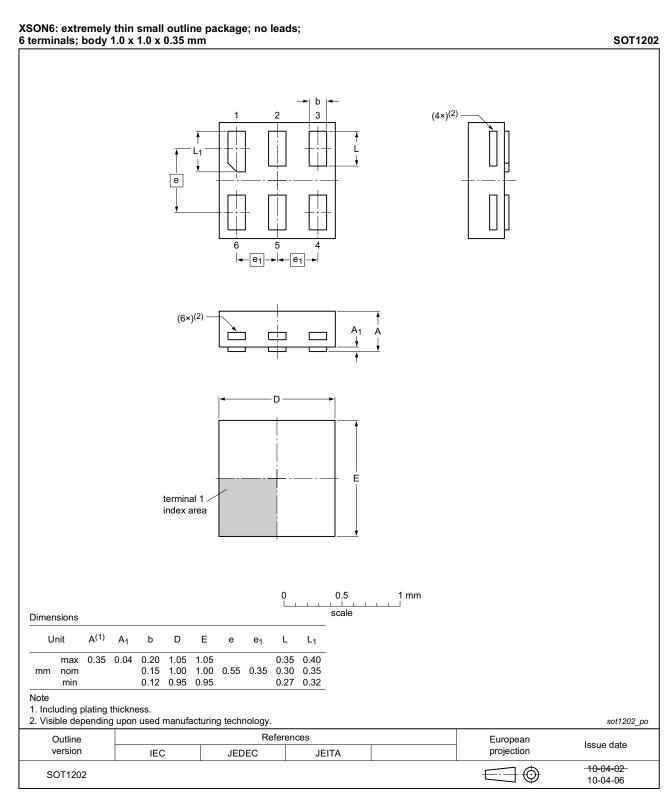


Fig 14. Package outline SOT1202 (XSON6)

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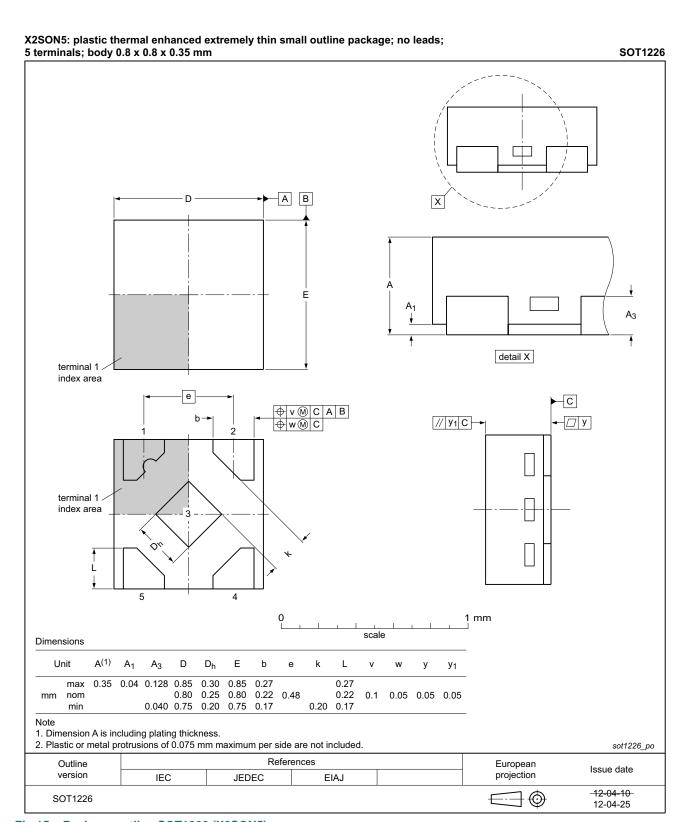


Fig 15. Package outline SOT1226 (X2SON5)

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## 14. Abbreviations

### Table 11. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

# 15. Revision history

### Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes			
74AUP1G38 v.7	20160404	Product data sheet	-	74AUP1G38 v.6			
Modifications:	Figure 7: Typo corrected in pin naming (pins A and B swapped)						
74AUP1G38 v.6	20120628	20628 Product data sheet -		74AUP1G38 v.5			
Modifications:	Added type nu	ımber 74AUP1G38GX (SOT	1226)				
	<ul> <li>Package outline drawing of SOT886 (<u>Figure 11</u>) modified.</li> </ul>						
74AUP1G38 v.5	20111129	1129 Product data sheet - 74A		74AUP1G38 v.4			
Modifications:	<ul> <li>Legal pages u</li> </ul>	pdated.					
74AUP1G38 v.4	20101007	Product data sheet	-	74AUP1G38 v.3			
74AUP1G38 v.3	20090622	Product data sheet	-	74AUP1G38 v.2			
74AUP1G38 v.2	20070614	Product data sheet	-	74AUP1G38 v.1			
74AUP1G38 v.1	20061020	Product data sheet	-	-			

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### 16. Legal information

#### 16.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
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